ABSTRACT

CHIP CARRIER INCORPORATING AN INTERLOCKING STRUCTURE

A lead frame and a method of manufacturing said lead frame is provided wherein a base material with first and second planar sides is first selectively etched from the first side thereof to a predetermined etching level to create etched areas. The etched areas on the first side of the said base material are then filled with a filling compound and thereafter, the base material is etched from the second side to the etching level to expose the filling compound on the second side.

(FIG. 3d)